

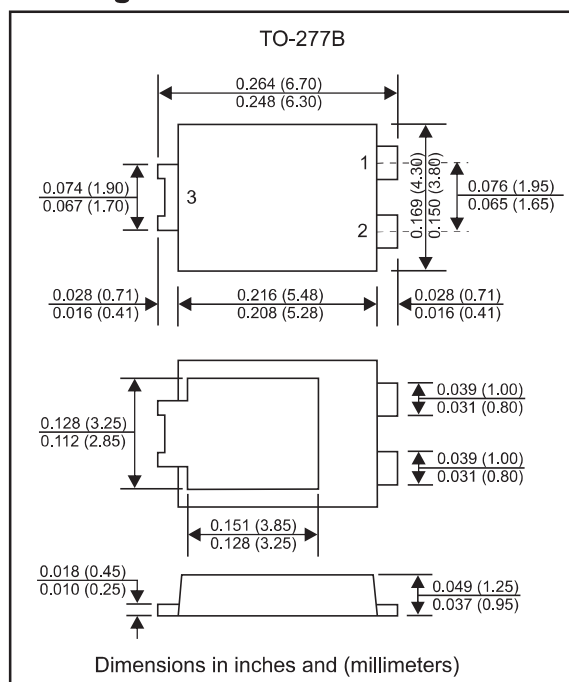
Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
260°C/10 seconds at terminals
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free

Mechanical data

- ◆ **Case:** JEDEC TO-277B molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

Package outline



Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	FSV20150V	Unit
DC Blocking Voltage Working Peak Reverse Voltage Repetitive Peak Reverse Voltage	V_{DC} V_{RWM} V_{RRM}	150	V
RMS Reverse Voltage	V_{RMS}	105	V
Average Forward Rectified Current	$I_{F(AV)}$	20.0	A
Peak Forward Surge Current, 8.3ms Half Sine-wave ($T_A=25^\circ\text{C}$)	I_{FSM}	280	A
Operating junction temperature range	T_J	-55 to +150	$^\circ\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	MIN.	TYP.	MAX.	Unit
Reverse Breakdown Voltage	$I_R=0.1\text{mA}$, $T_J=25^\circ\text{C}$	V_B	150	-	-	V
Forward voltage	$I_F=20\text{A}$, $T_J=25^\circ\text{C}$	V_F			0.84	V
Reverse current	$V_R=150\text{V}$, $T_J=25^\circ\text{C}$	I_R			0.05	mA
	$V_R=150\text{V}$, $T_J=125^\circ\text{C}$				10	

Rating and characteristic curves

FIG.1: Forward Output Current Derating Curve

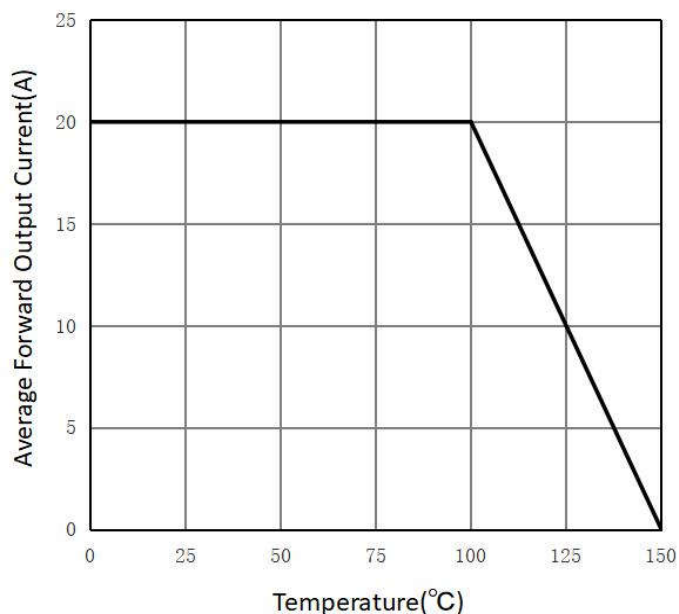


FIG.2: Maximum Non-Repetitive Peak Forward Surge Current

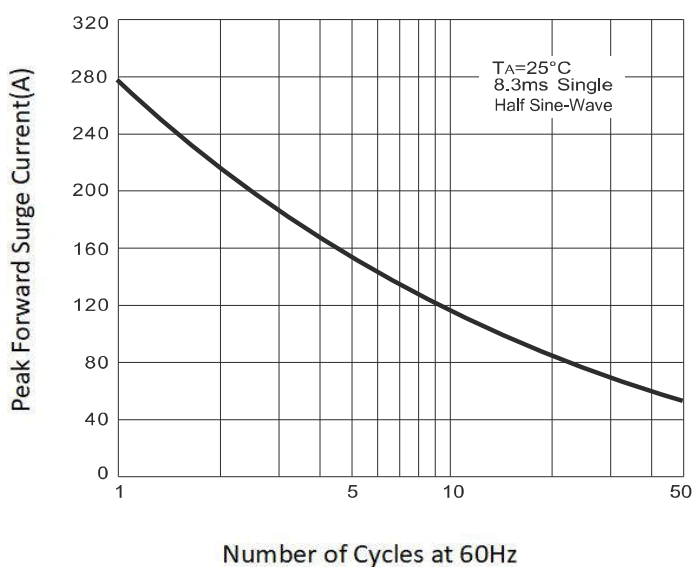


FIG.3: Typical Forward Characteristics

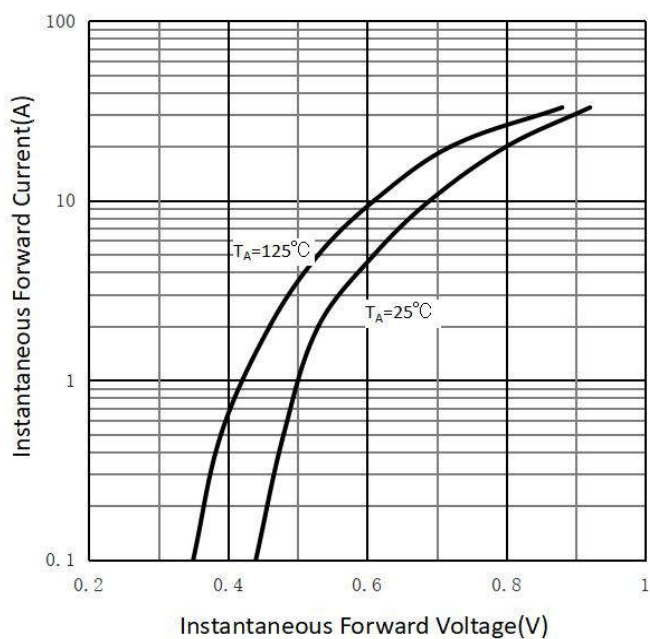
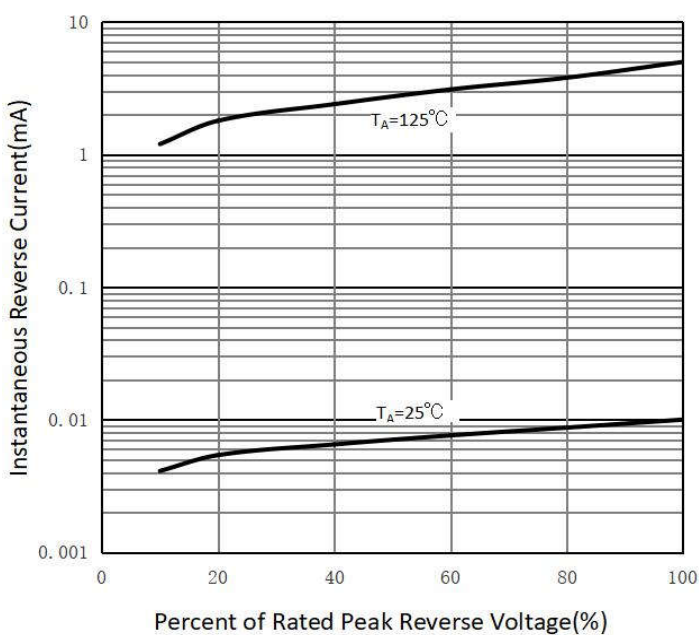
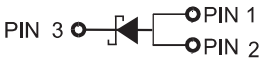


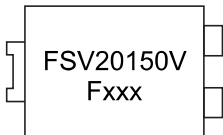
FIG.4: Typical Reverse Characteristics



Pinning information

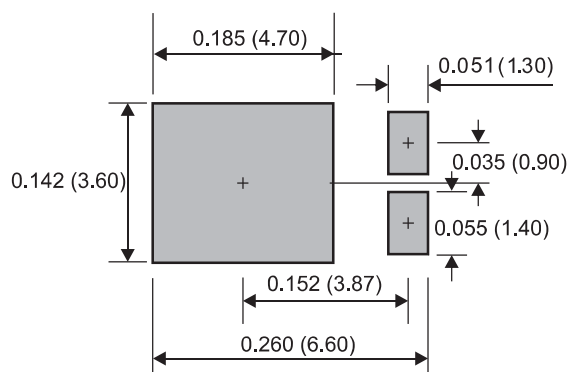
Pin	Simplified outline	Symbol
Pin3 cathode Pin1 anode Pin2 anode		

Marking

Type number	Marking code
FSV20150V	

Suggested solder pad layout

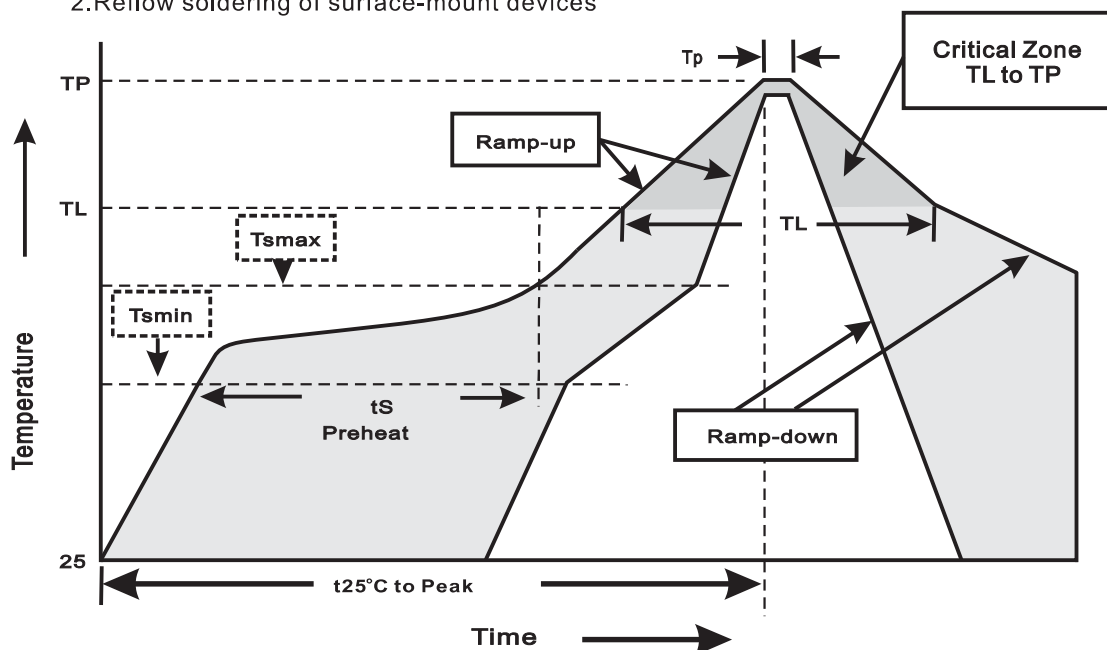
TO-277B



Dimensions in inches and (millimeters)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{min}) -Temperature Max(T _{max}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{max} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes